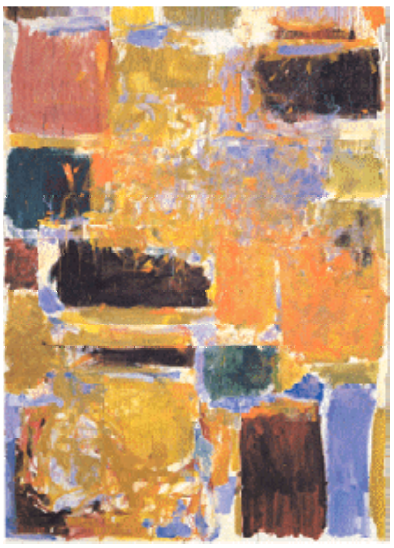


Digital Integrated Circuits
A Design Perspective

Jan M. Rabaey
Anantha Chandrakasan
Borivoje Nikolic

Semiconductor Memories

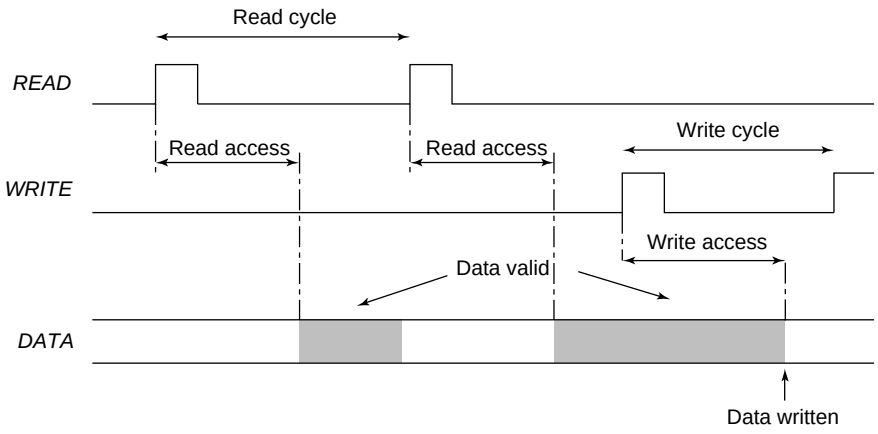
Chapter Overview

- Memory Classification
- Memory Architectures
- The Memory Core
- Periphery
- Reliability
- Case Studies

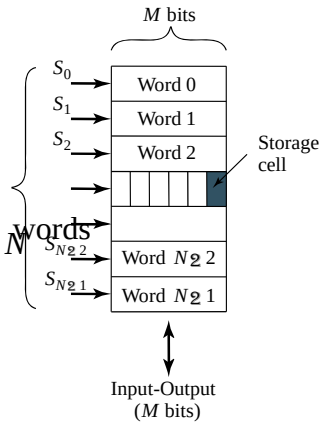
Semiconductor Memory Classification

Read-Write Memory		Non-Volatile Read-Write Memory	Read-Only Memory
Random Access	**Non-Random Access**	EPROM E^2PROM FLASH	Mask-Programmed Programmable (PROM)
SRAM DRAM	FIFO LIFO Shift Register CAM		

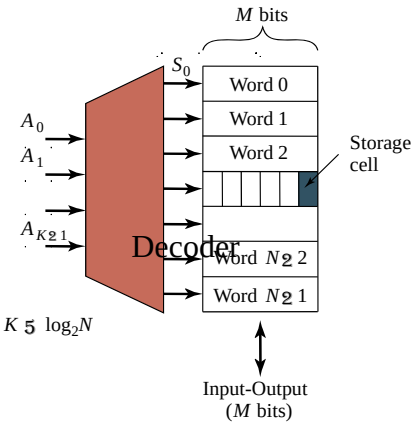
Memory Timing: Definitions



Memory Architecture: Decoders



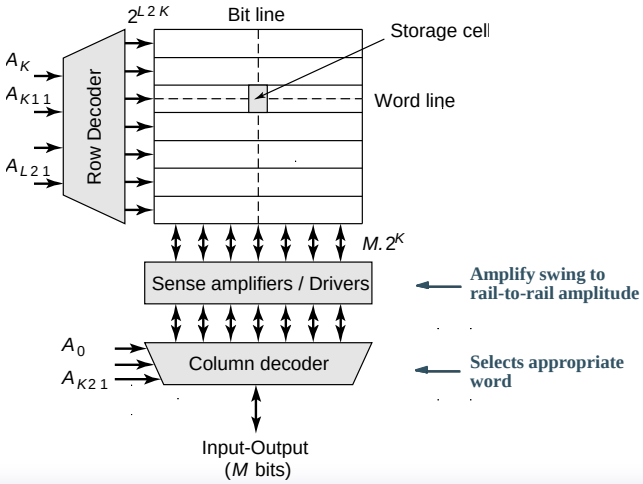
Intuitive architecture for N x M memory
Too many select signals:
N words == N select signals



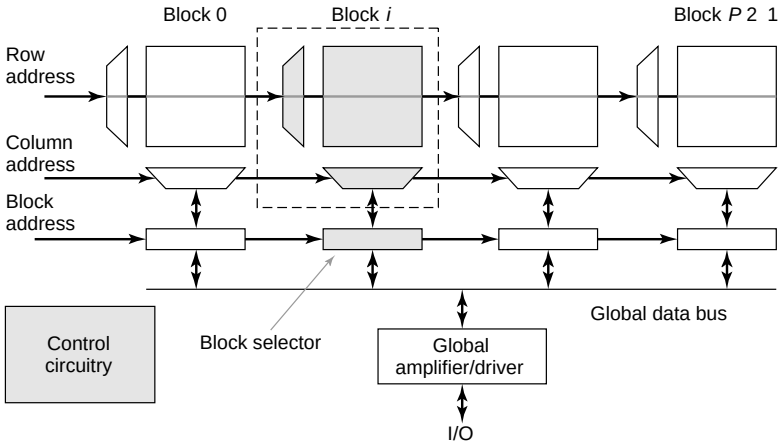
Decoder reduces the number of select signals
$K = log_2 N$

Array-Structured Memory Architecture

Problem: ASPECT RATIO or HEIGHT >> WIDTH



Hierarchical Memory Architecture

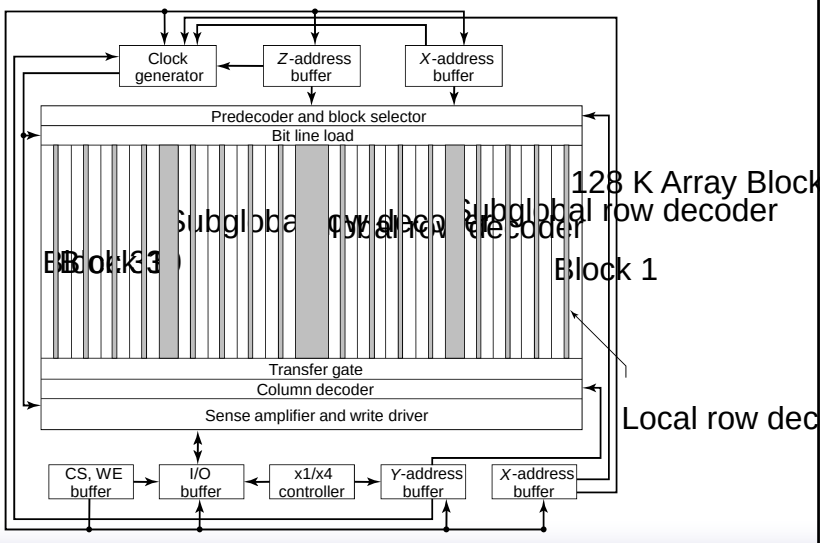


Advantages:

1. Shorter wires within blocks

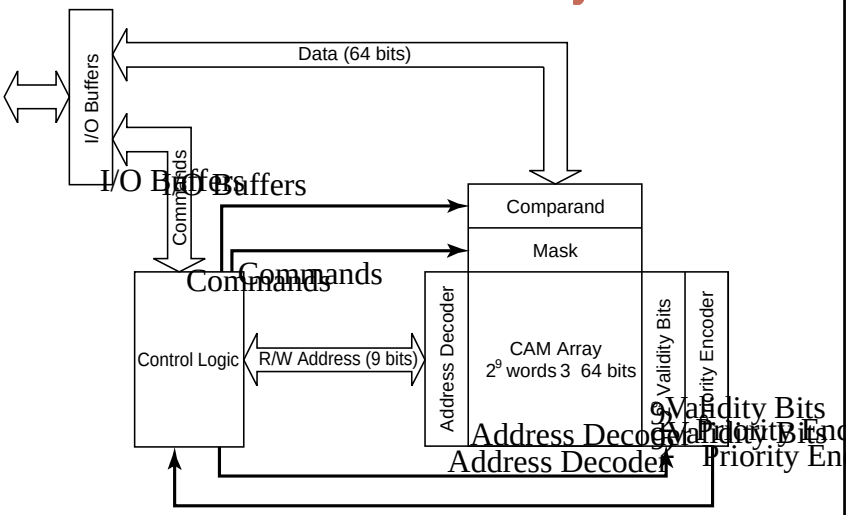
2. Block address activates only 1 block => power savings

Block Diagram of 4 Mbit SRAM

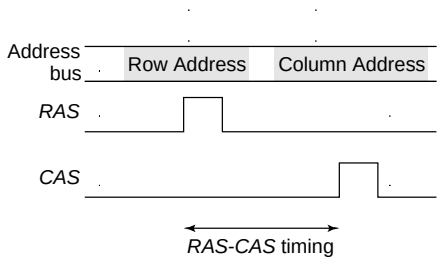


[Hirose90]

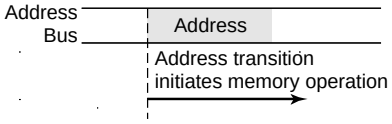
Contents-Addressable Memory



Memory Timing: Approaches

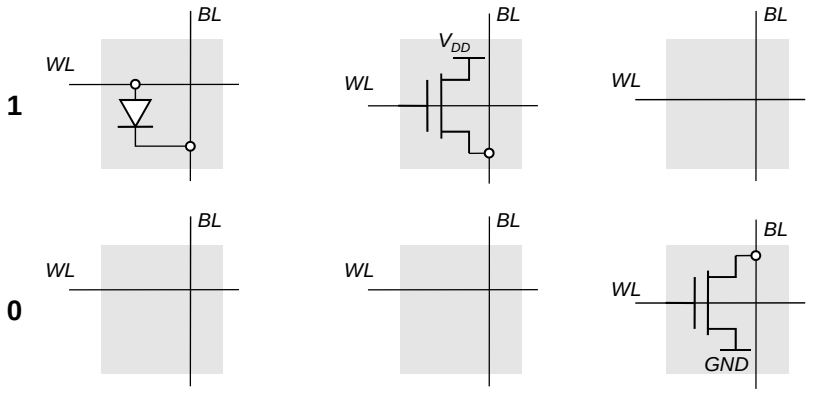


DRAM Timing
Multiplexed Adressing

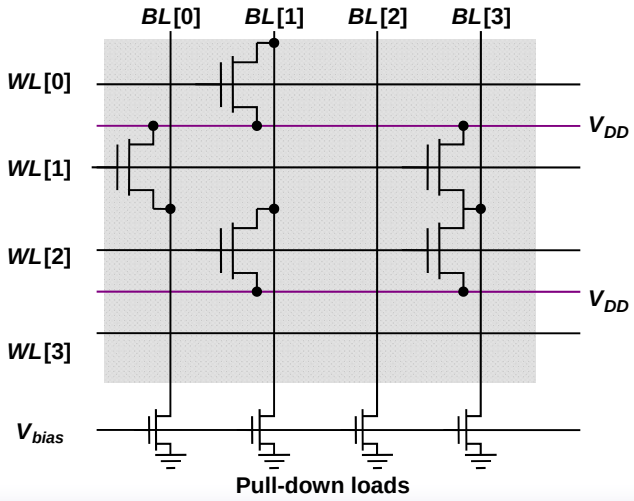


SRAM Timing
Self-timed

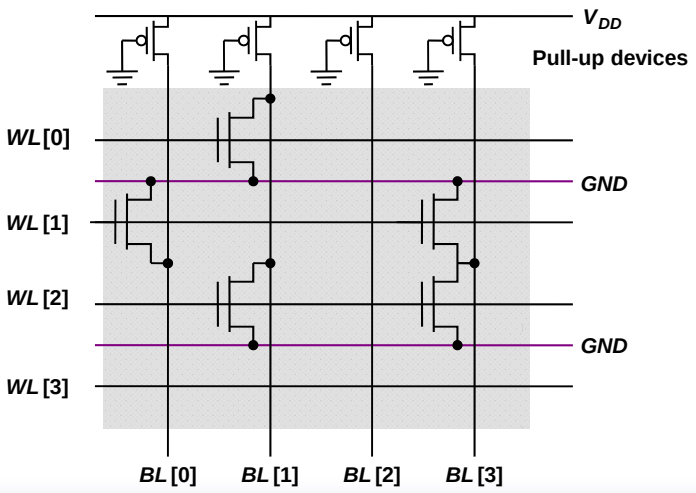
Read-Only Memory Cells



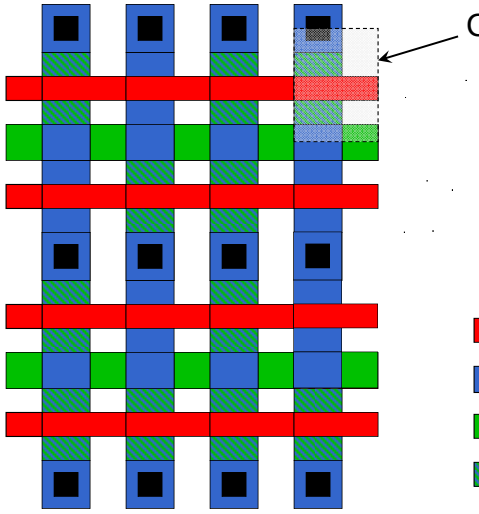
MOS OR ROM



MOS NOR ROM



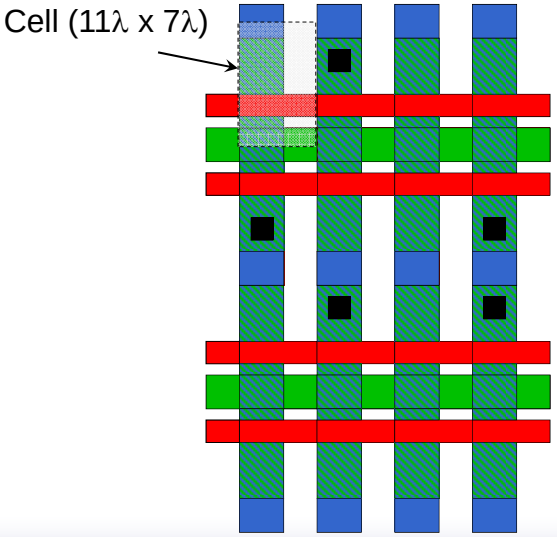
MOS NOR ROM Layout



Programmming using the Active Layer Only

Polysilicon
Metal1
Diffusion
Metal1 on Diffusion

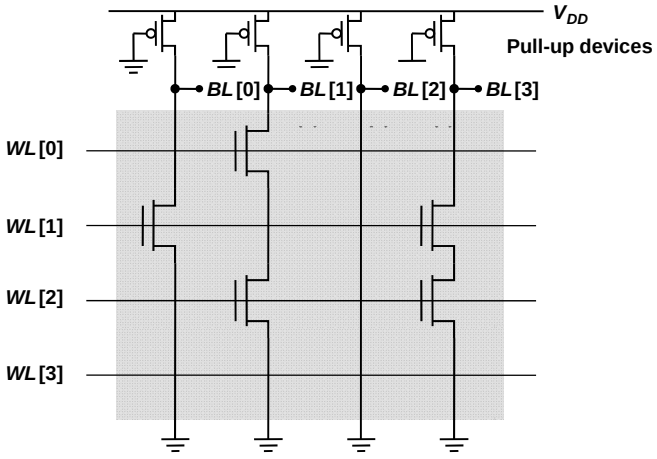
MOS NOR ROM Layout



Programmming using the Contact Layer Only

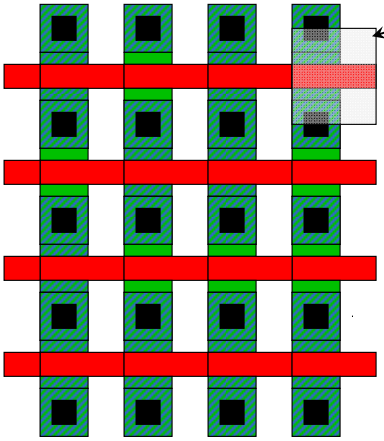
Polysilicon
Metal1
Diffusion
Metal1 on Diffusion

MOS NAND ROM



All word lines high by default with exception of selected row

MOS NAND ROM Layout

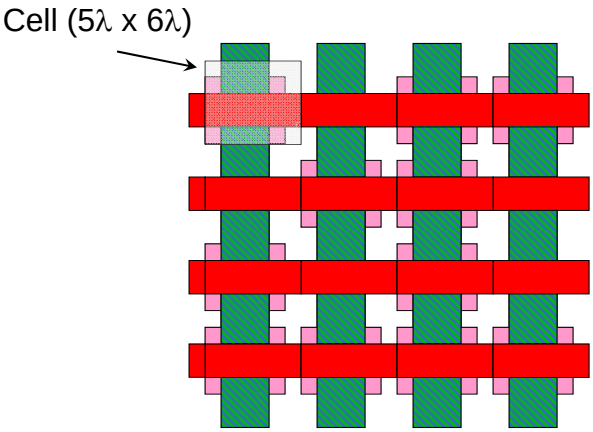


Programmming using the Metal-1 Layer Only

No contact to VDD or GND necessary; drastically reduced cell size
Loss in performance compared to NOR ROM

Polysilicon
Diffusion
Metal1 on Diffusion

NAND ROM Layout

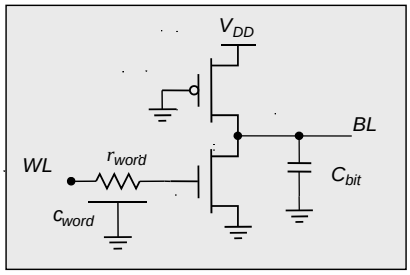


Programmming using Implants Only

Polysilicon
Threshold-altering implant
Metal1 on Diffusion

Equivalent Transient Model for MOS NOR ROM

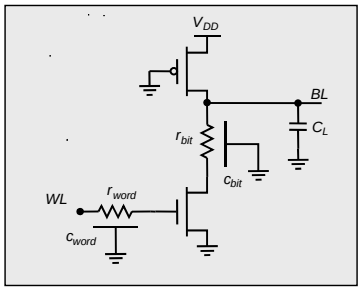
Model for NOR ROM



- Word line parasitics
  - Wire capacitance and gate capacitance
  - Wire resistance (polysilicon)
- Bit line parasitics
  - Resistance not dominant (metal)
  - Drain and Gate-Drain capacitance

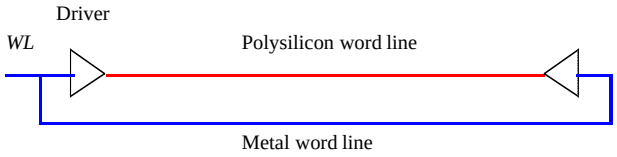
Equivalent Transient Model for MOS NAND ROM

Model for NAND ROM

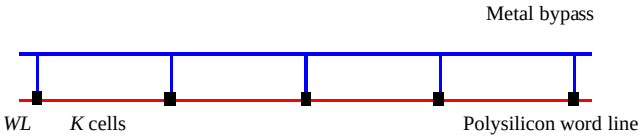


- Word line parasitics
  - Similar to NOR ROM
- Bit line parasitics
  - Resistance of cascaded transistors dominates
  - Drain/Source and complete gate capacitance

Decreasing Word Line Delay



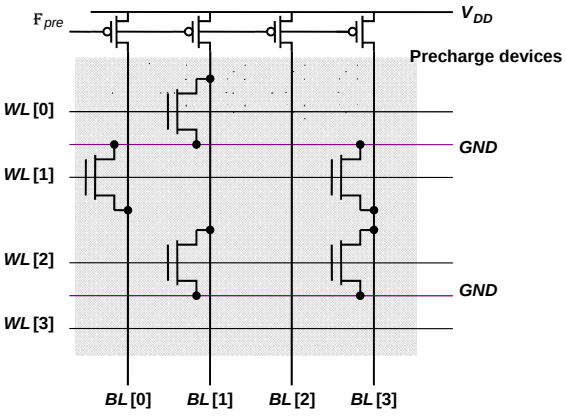
(a) Driving the word line from both sides



(b) Using a metal bypass

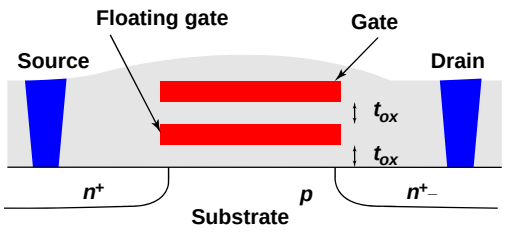
(c) Use silicides

Precharged MOS NOR ROM

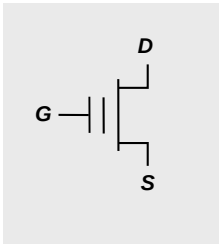


PMOS precharge device can be made as large as necessary, but clock driver becomes harder to design.

Non-Volatile Memories
The Floating-gate transistor (FAMOS)

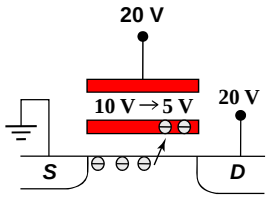


Device cross-section

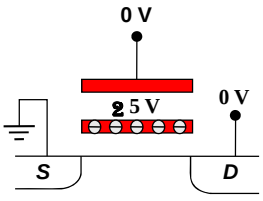


Schematic symbol

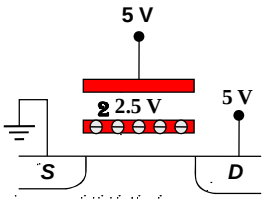
Floating-Gate Transistor Programming



Avalanche injection

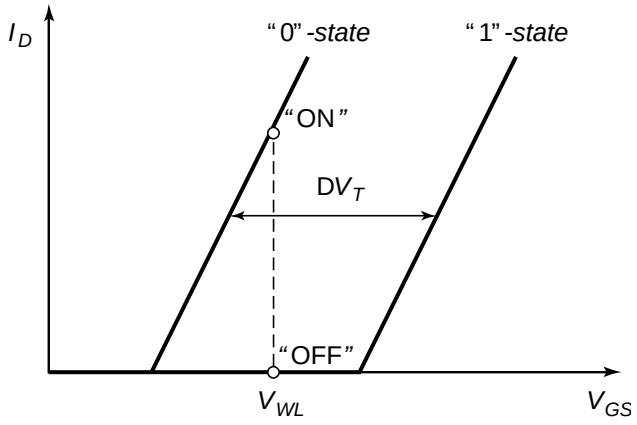


Removing programming voltage leaves charge trapped

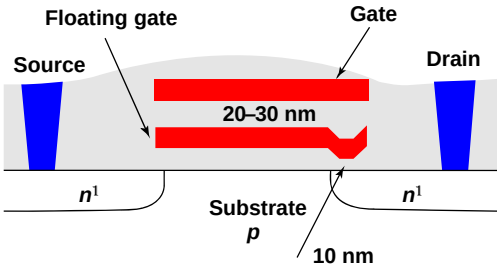


Programming results in higher V_T.

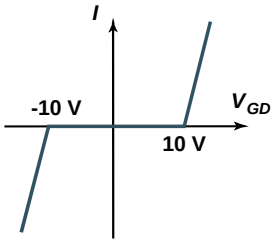
A "Programmable-Threshold" Transistor



FLOTOX EEPROM

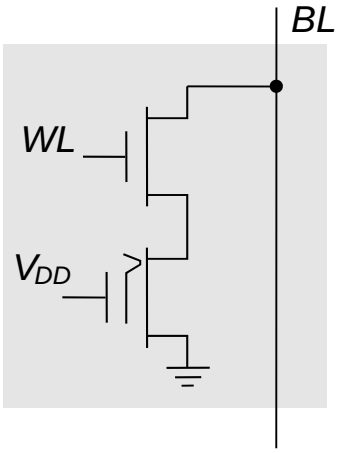


FLOTOX transistor



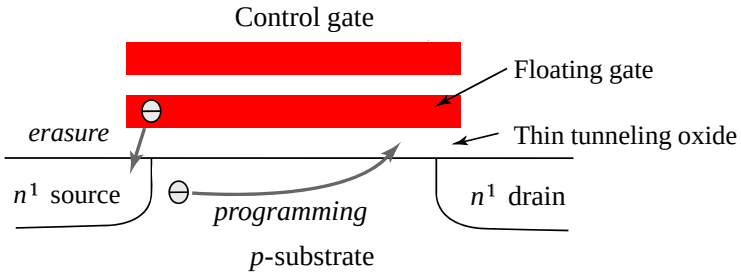
Fowler-Nordheim
I-V characteristic

EEPROM Cell



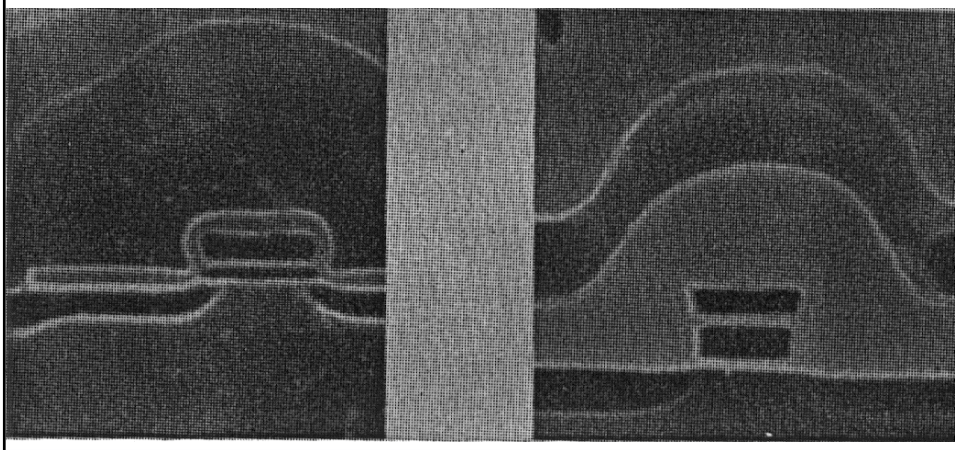
Absolute threshold control is hard
Unprogrammed transistor might be depletion
⇨ 2 transistor cell

Flash EEPROM



Many other options …

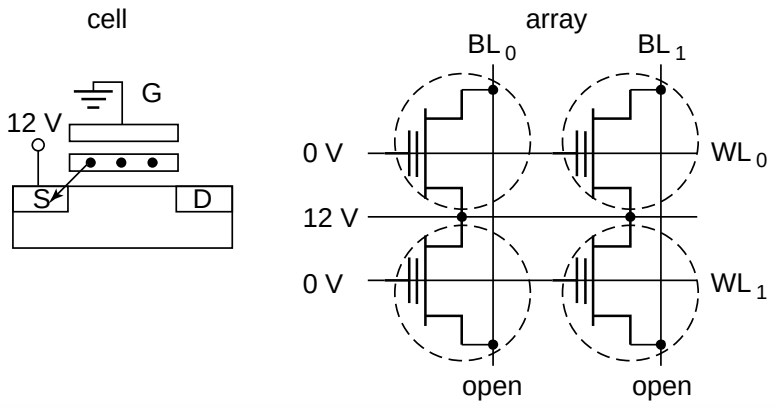
Cross-sections of NVM cells



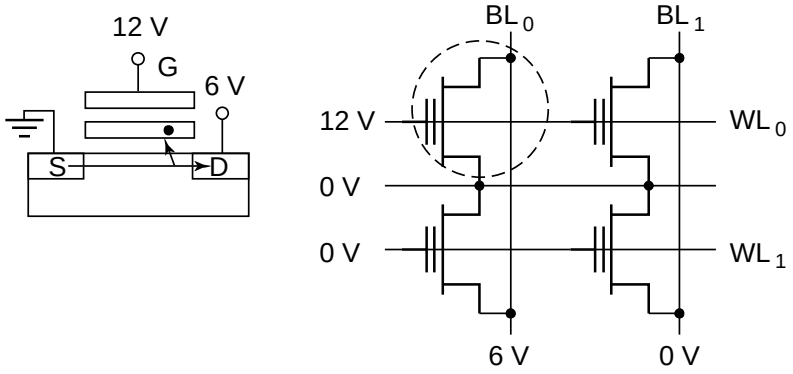
Flash EPROM

Courtesy Intel

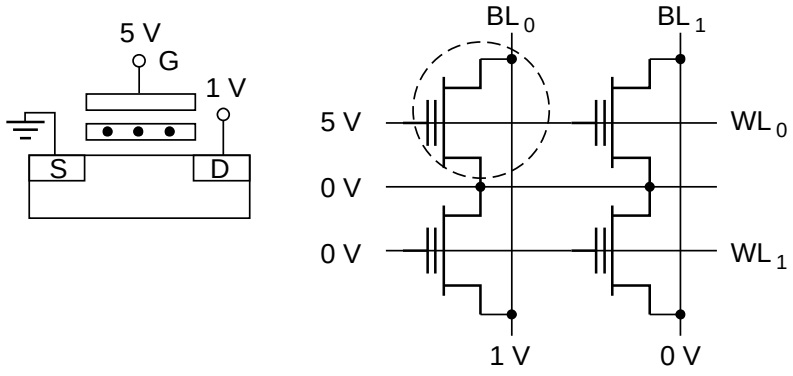
Basic Operations in a NOR Flash Memory—Erase



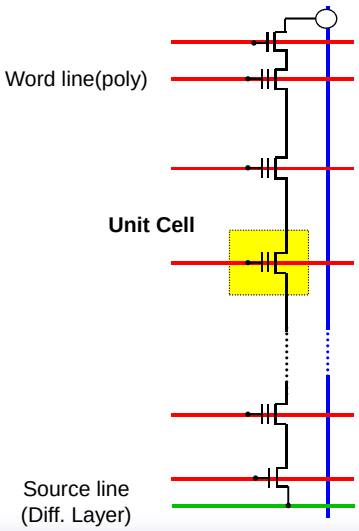
Basic Operations in a NOR Flash Memory—Write

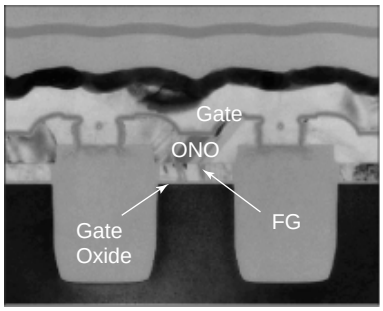


Basic Operations in a NOR Flash Memory—Read



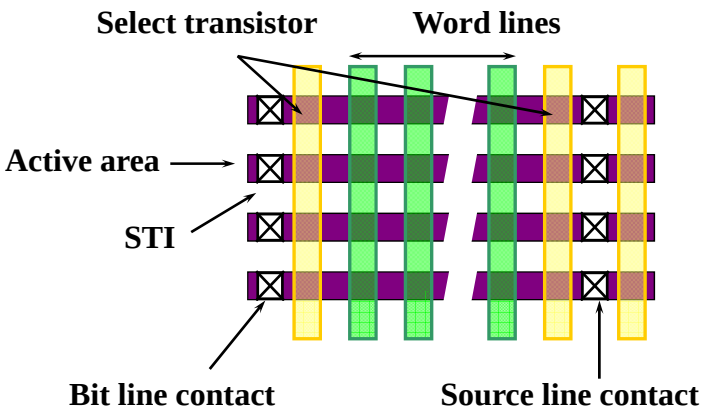
NAND Flash Memory





Courtesy Toshiba

NAND Flash Memory



Courtesy Toshiba

Characteristics of State-of-the-art NVM

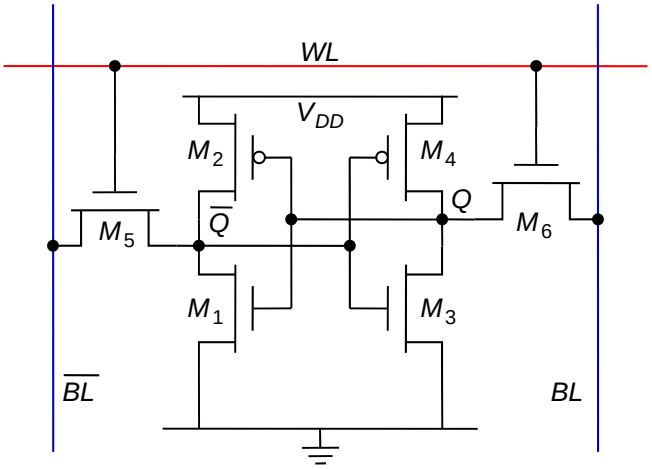
Table 12-1 Comparison between nonvolatile memories ([Itoh01]).
V_{DD} = 3.3 or 5 V; V_{PP} = 12 or 12.5 V.

	Cell—Nr. of Transistors	Cell Area (ratio wrt EPROM)	Mechanism		External Power Supply		Program/ Erase Cycles
			Erase	Write	Write	Read	
MASK ROM	1 T (NAND)	0.35–5	—	—	—	V_{DD}	0
EPROM	1 T	1	UV Exposure	Hot electrons	V_{PP}	V_{DD}	~100
EEPROM	2 T	3–5	FN Tunneling	FN Tunneling	V_{PP} (int)	V_{DD}	10^4–10^5
Flash Memory	1 T	1–2	FN Tunneling	Hot electrons	V_{PP}	V_{DD}	10^4–10^5
			FN Tunneling	FN Tunneling	V_{PP} (int)	V_{DD}	10^4–10^5

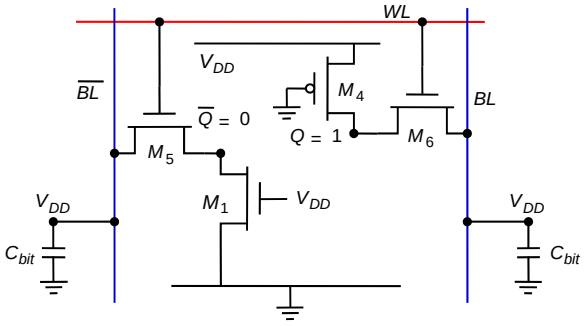
Read-Write Memories (RAM)

- **STATIC (SRAM)**
  - Data stored as long as supply is applied
  - Large (6 transistors/cell)
  - Fast
  - Differential
- **DYNAMIC (DRAM)**
  - Periodic refresh required
  - Small (1-3 transistors/cell)
  - Slower
  - Single Ended

6-transistor CMOS SRAM Cell



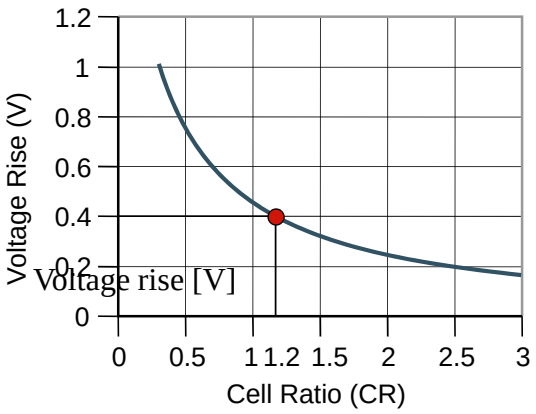
CMOS SRAM Analysis (Read)



$$k_{n,M5}\left((V_{DD}-\Delta V-V_{Tn})V_{DSATn}-\frac{V_{DSATn}^2}{2}\right) = k_{n,M1}\left((V_{DD}-V_{Tn})\Delta V-\frac{\Delta V^2}{2}\right)$$

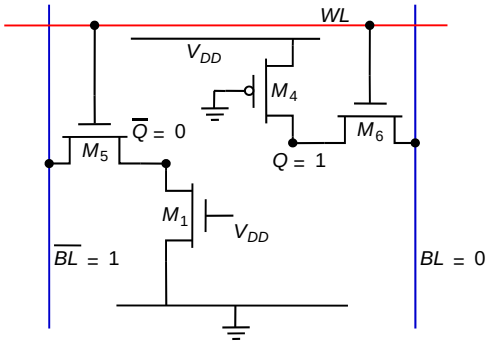
$$\Delta V = \frac{V_{DSATn}+CR(V_{DD}-V_{Tn})-\sqrt{V_{DSATn}^2(1+CR)+CR^2(V_{DD}-V_{Tn})^2}}{CR}$$

CMOS SRAM Analysis (Read)



$$CR = \frac{W_1/L_1}{W_5/L_5}$$

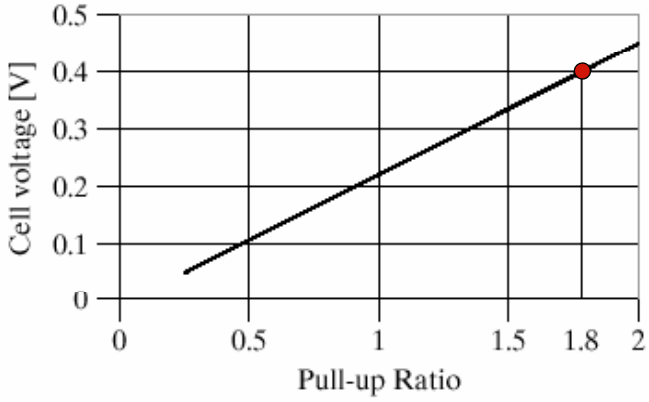
CMOS SRAM Analysis (Write)



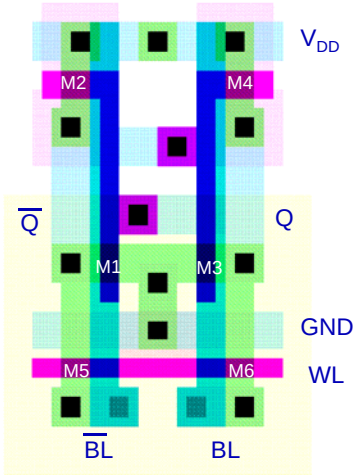
$$k_{n,M6}\left((V_{DD}-V_{Tn})V_Q-\frac{V_Q^2}{2}\right) = k_{p,M4}\left((V_{DD}-|V_{Tp}|)V_{DSATp}-\frac{V_{DSATp}^2}{2}\right)$$

$$V_Q = V_{DD}-V_{Tn}-\sqrt{(V_{DD}-V_{Tn})^2-2\frac{\mu_p}{\mu_n}PR\left((V_{DD}-|V_{Tp}|)V_{DSATp}-\frac{V_{DSATp}^2}{2}\right)},$$

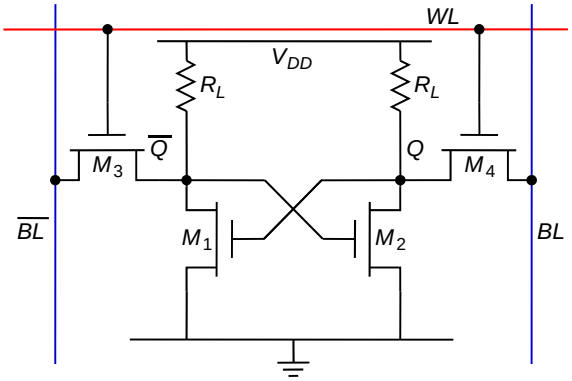
CMOS SRAM Analysis (Write)



6T-SRAM — Layout



Resistance-load SRAM Cell



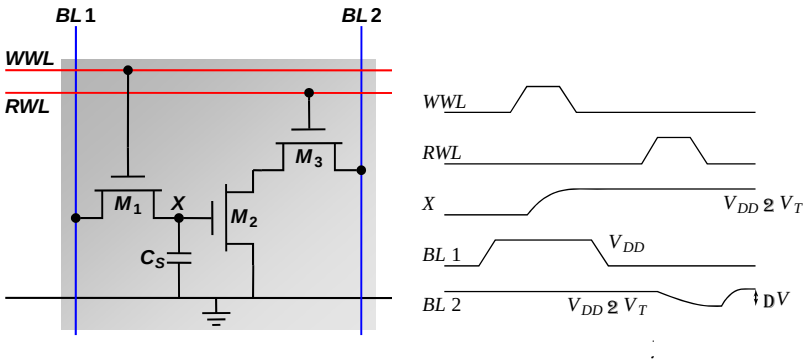
Static power dissipation -- Want R_L large
Bit lines precharged to V_{DD} to address t_p problem

SRAM Characteristics

Table 12-2 Comparison of CMOS SRAM cells used in 1-Mbit memory (from [Takada91])

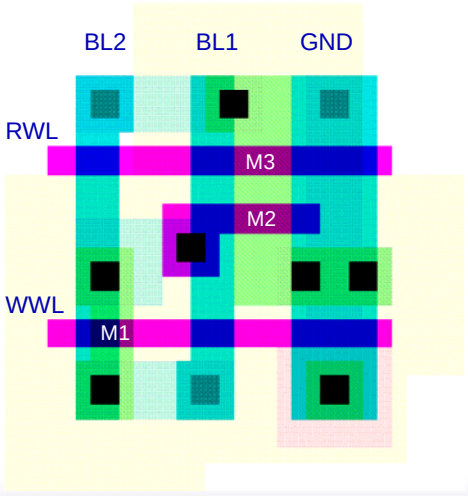
	Complementary CMOS	Resistive Load	TFT Cell
Number of transistors	6	4	4 (+2 TFT)
Cell size	58.2 μm^2 (0.7-µm rule)	40.8 μm^2 (0.7-µm rule)	41.1 μm^2 (0.8-µm rule)
Standby current (per cell)	10^{-15} A	10^{-12} A	10^{-13} A

3-Transistor DRAM Cell

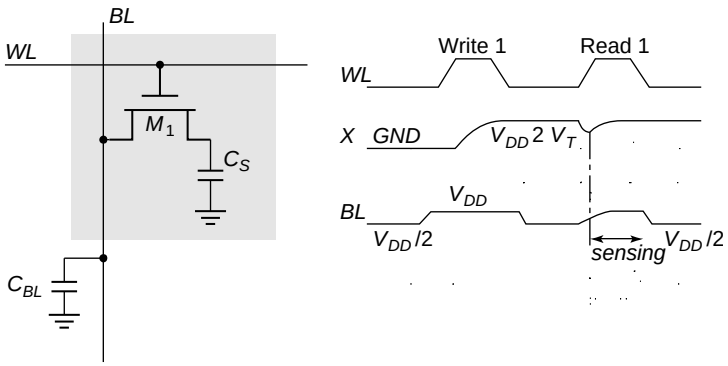


No constraints on device ratios
Reads are non-destructive
Value stored at node X when writing a "1" = V_{WWL}-V_{Tn}

3T-DRAM — Layout



1-Transistor DRAM Cell



Write: C_S is charged or discharged by asserting WL and BL.
Read: Charge redistribution takes places between bit line and storage capacitance

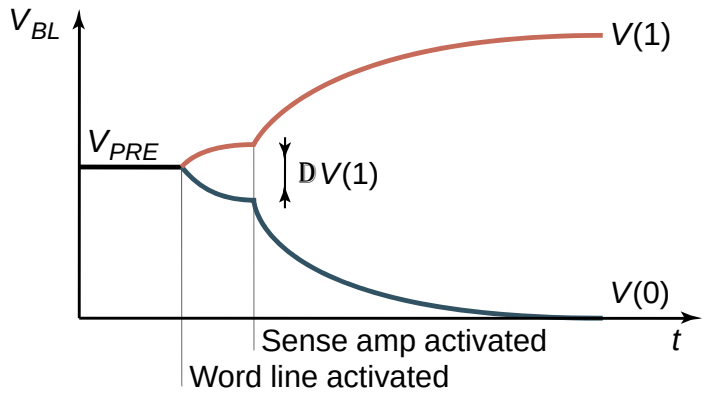
$$\Delta V = V_{BL} - V_{PRE} = V_{BIT} - V_{PRE} \frac{C_S}{C_S + C_{BL}}$$

Voltage swing is small; typically around 250 mV.

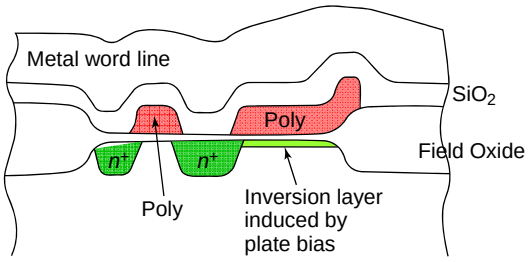
DRAM Cell Observations

- 1T DRAM requires a sense amplifier for each bit line, due to charge redistribution read-out.
- DRAM memory cells are single ended in contrast to SRAM cells.
- The read-out of the 1T DRAM cell is destructive; read and refresh operations are necessary for correct operation.
- Unlike 3T cell, 1T cell requires presence of an extra capacitance that must be explicitly included in the design.
- When writing a "1" into a DRAM cell, a threshold voltage is lost. This charge loss can be circumvented by bootstrapping the word lines to a higher value than V_{DD}

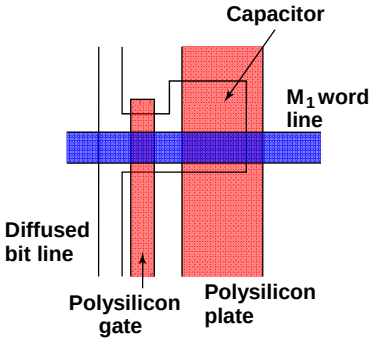
Sense Amp Operation



1-T DRAM Cell



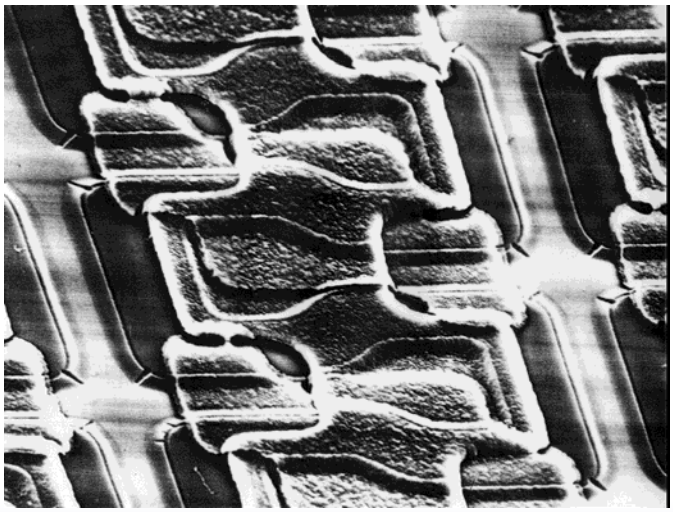
Cross-section



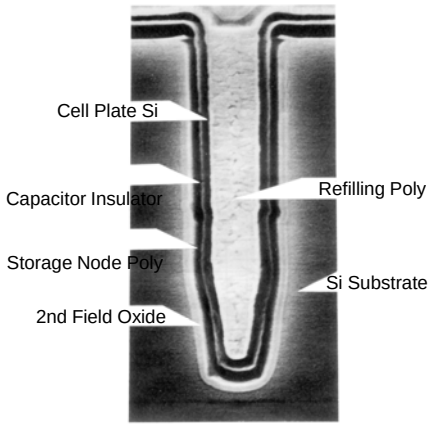
Layout

Uses Polysilicon-Diffusion Capacitance
Expensive in Area

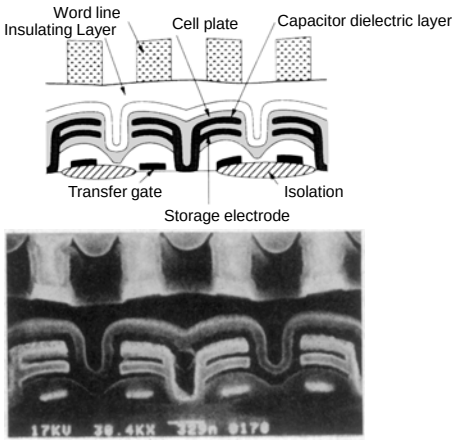
SEM of poly-diffusion capacitor 1T-DRAM



Advanced 1T DRAM Cells

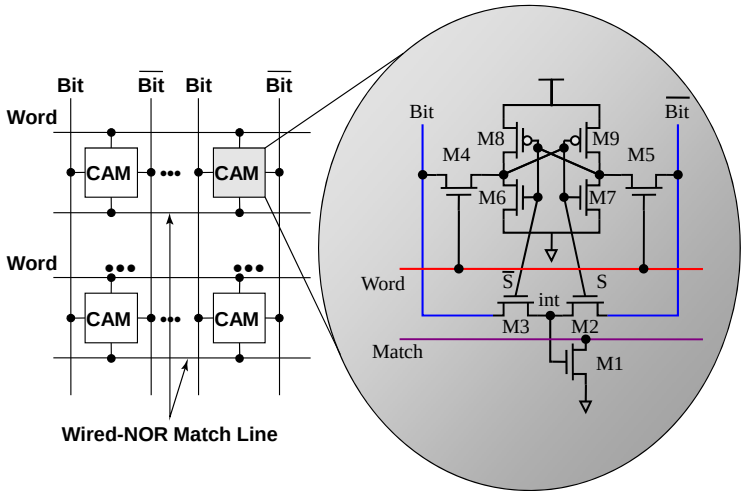


Trench Cell

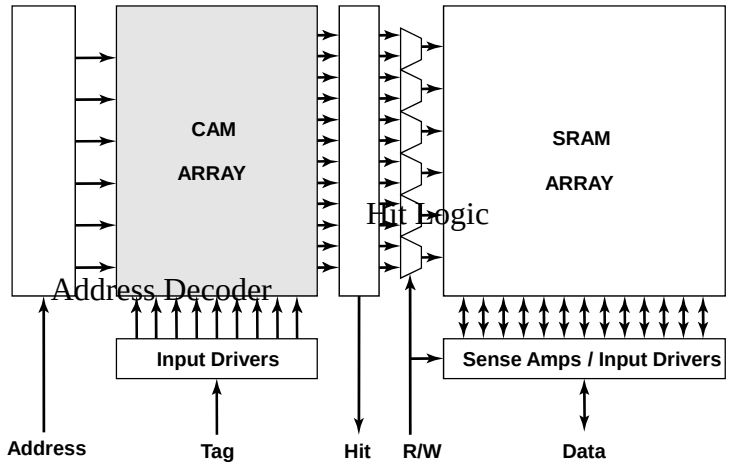


Stacked-capacitor Cell

Static CAM Memory Cell



CAM in Cache Memory



Periphery

- Decoders
- Sense Amplifiers
- Input/Output Buffers
- Control / Timing Circuitry

Row Decoders

Collection of 2^M complex logic gates
Organized in regular and dense fashion

(N)AND Decoder

$$WL_0 = A_0 A_1 A_2 A_3 A_4 A_5 A_6 A_7 A_8 A_9$$

$$WL_{511} = \bar{A}_0 A_1 A_2 A_3 A_4 A_5 A_6 A_7 A_8 A_9$$

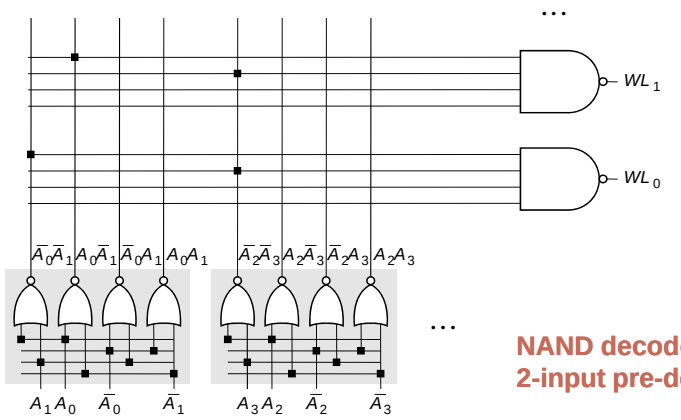
NOR Decoder

$$WL_0 = \overline{A_0 + A_1 + A_2 + A_3 + A_4 + A_5 + A_6 + A_7 + A_8 + A_9}$$

$$WL_{511} = \overline{A_0 + \bar{A}_1 + \bar{A}_2 + \bar{A}_3 + \bar{A}_4 + \bar{A}_5 + \bar{A}_6 + \bar{A}_7 + \bar{A}_8 + \bar{A}_9}$$

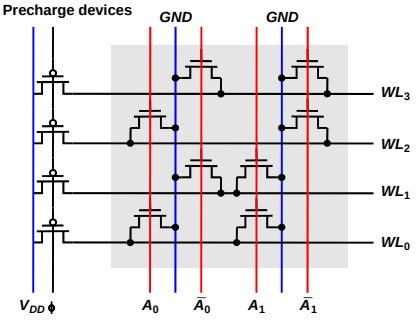
Hierarchical Decoders

Multi-stage implementation improves performance

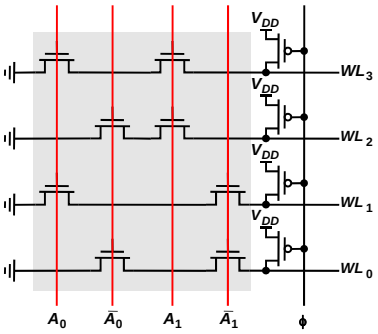


NAND decoder using 2-input pre-decoders

Dynamic Decoders

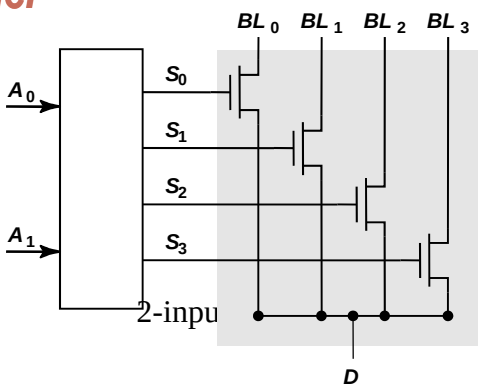


2-input NOR decoder



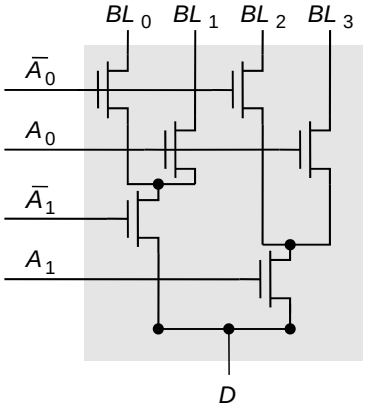
2-input NAND decoder

4-input pass-transistor based column decoder



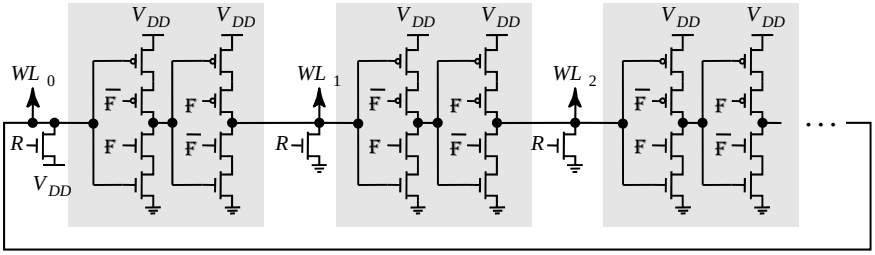
Advantages: speed (t_{pd} does not add to overall memory access time)
Only one extra transistor in signal path
Disadvantage: Large transistor count

4-to-1 tree based column decoder



Number of devices drastically reduced
Delay increases quadratically with # of sections; prohibitive for large decoders
Solutions: buffers
progressive sizing
combination of tree and pass transistor approaches

Decoder for circular shift-register



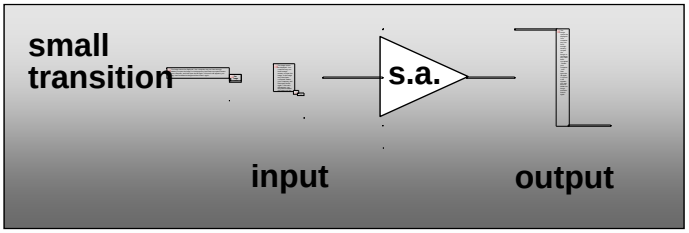
Sense Amplifiers

$$t_p = \frac{C \times \Delta V}{I_{av}}$$

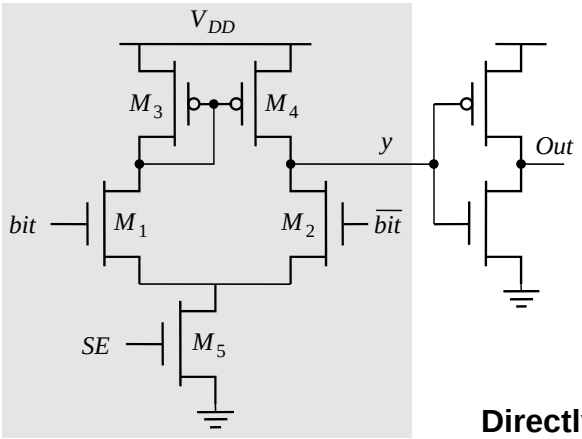
make ΔV as small as possible

large small

Idea: Use Sense Amplifer

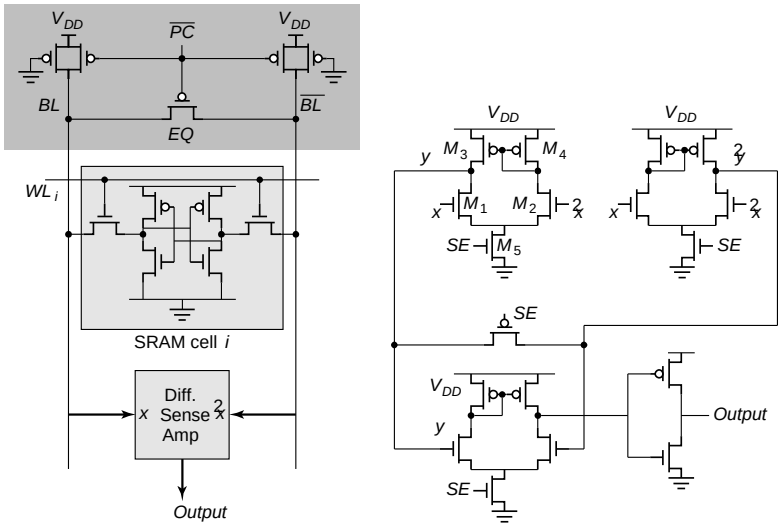


Differential Sense Amplifier



Directly applicable to SRAMs

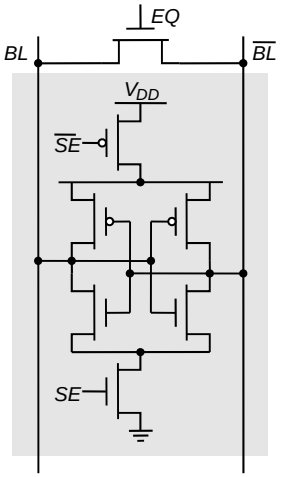
Differential Sensing – SRAM



(a) SRAM sensing scheme

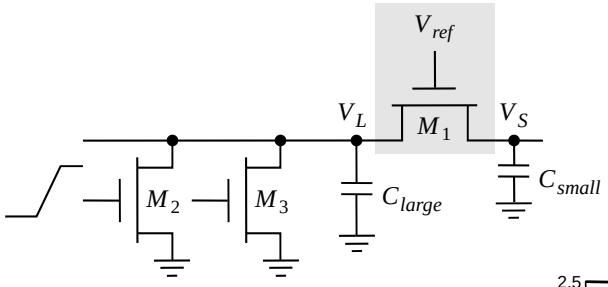
(b) two stage differential amplifier

Latch-Based Sense Amplifier (DRAM)



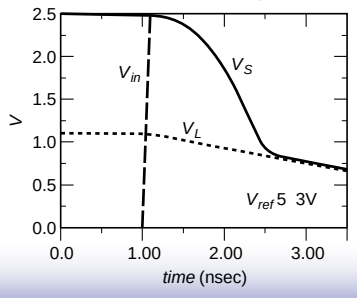
Initialized in its meta-stable point with EQ
Once adequate voltage gap created, sense amp enabled with SE
Positive feedback quickly forces output to a stable operating point.

Charge-Redistribution Amplifier

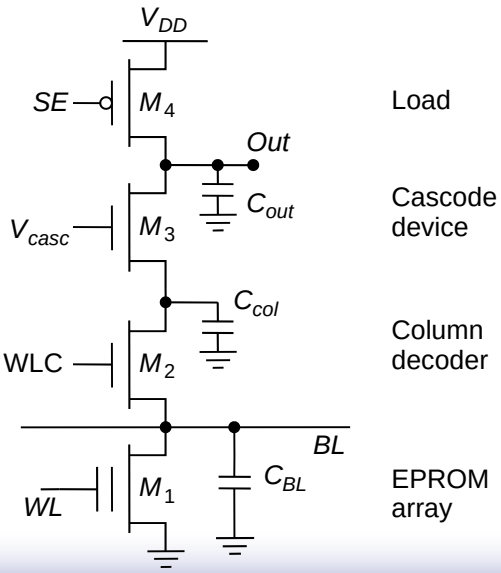


Concept

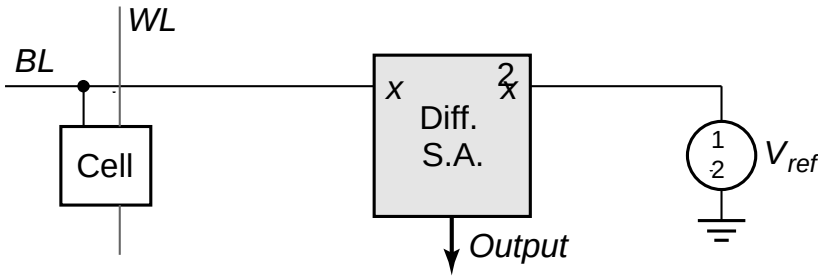
Transient Response



Charge-Redistribution Amplifier—EPROM

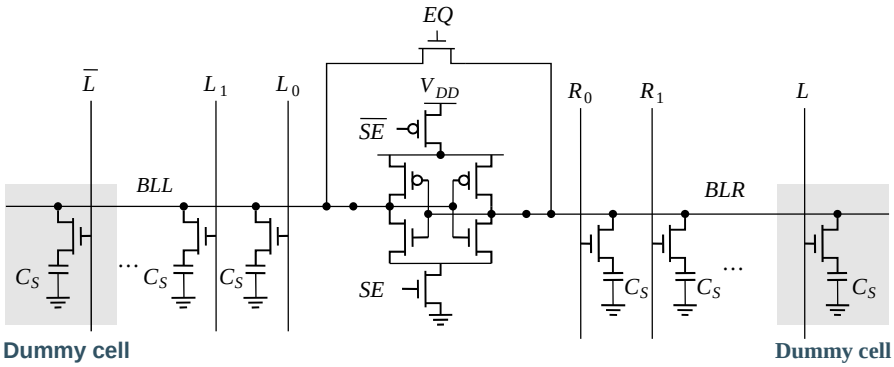


Single-to-Differential Conversion

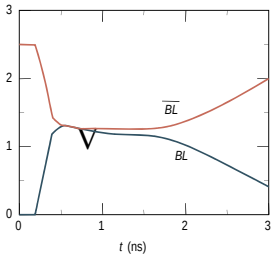


How to make a good V_{ref}?

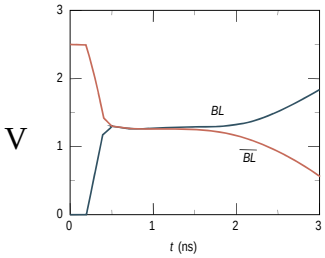
Open bitline architecture with dummy cells



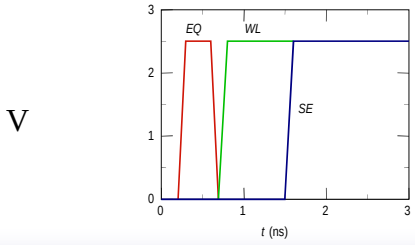
DRAM Read Process with Dummy Cell



reading 0

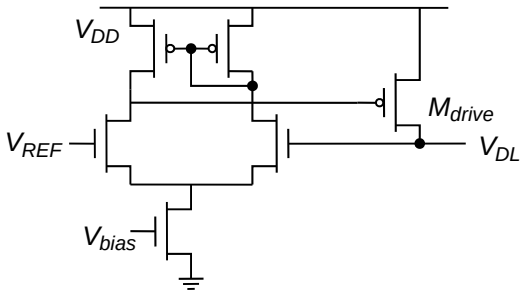


reading 1

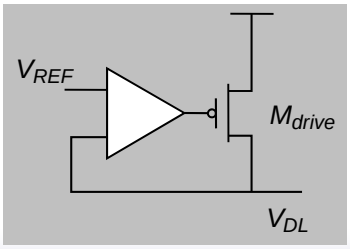


control signals

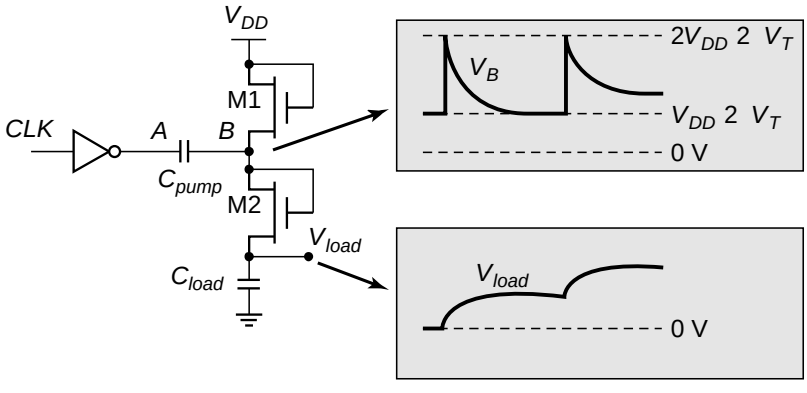
Voltage Regulator



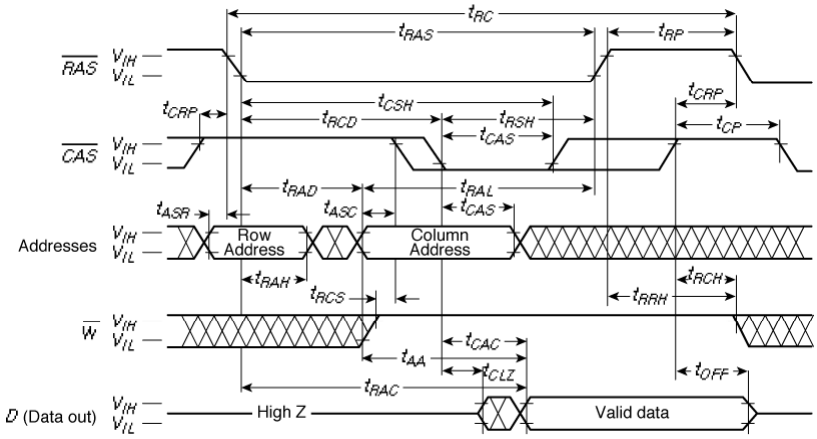
Equivalent Model



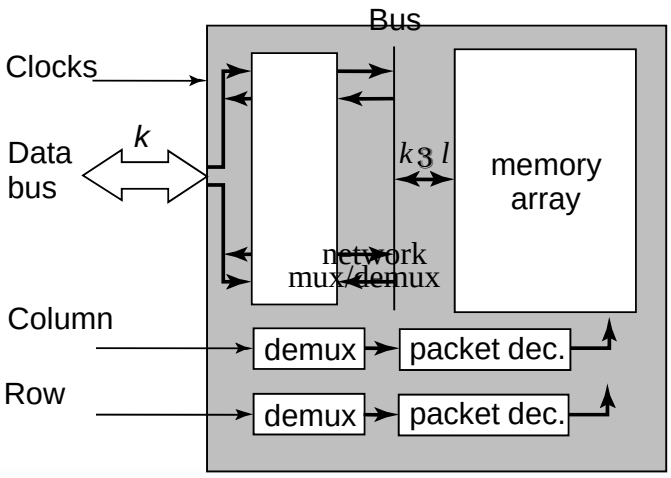
Charge Pump



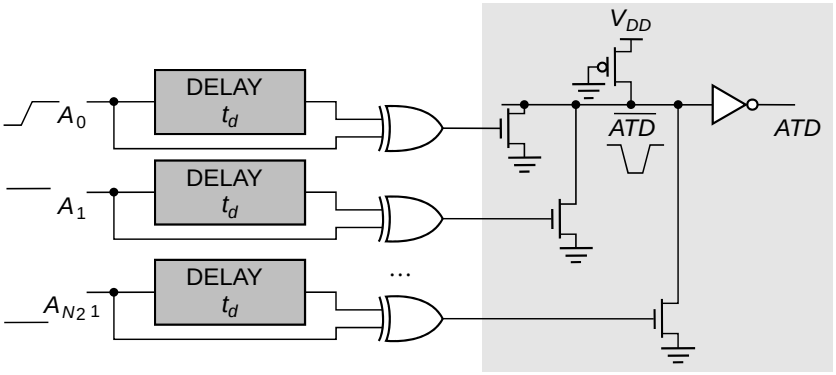
DRAM Timing



RDRAM Architecture

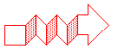


Address Transition Detection



Reliability and Yield

- Semiconductor memories trade off noise-margin for density and performance



Highly Sensitive to Noise (Crosstalk, Supply Noise)

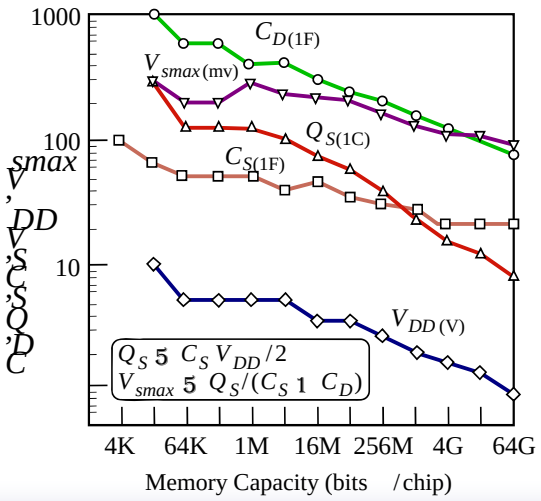
- High Density and Large Die size cause Yield Problems

$$Y = 100\frac{Number\ of\ Good\ Chips\ on\ Wafer}{Number\ of\ Chips\ on\ Wafer}$$

$$Y = \left[\frac{1 - e^{-AD}}{AD}\right]^2$$

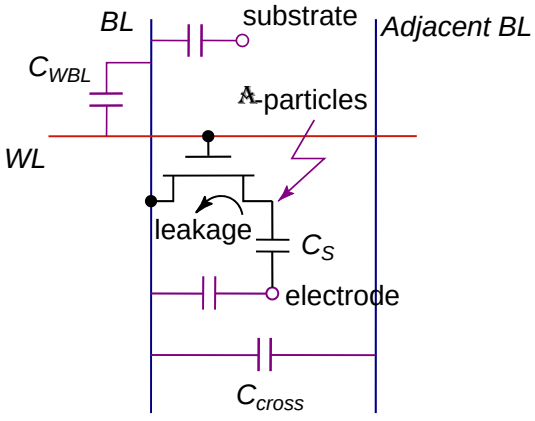
Increase Yield using Error Correction and Redundancy

Sensing Parameters in DRAM

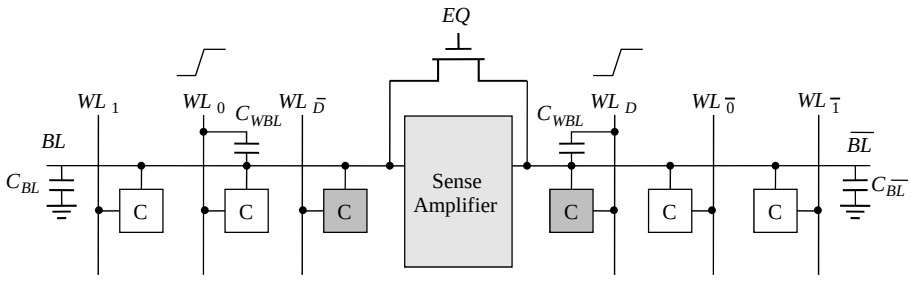


From [Itoh01]

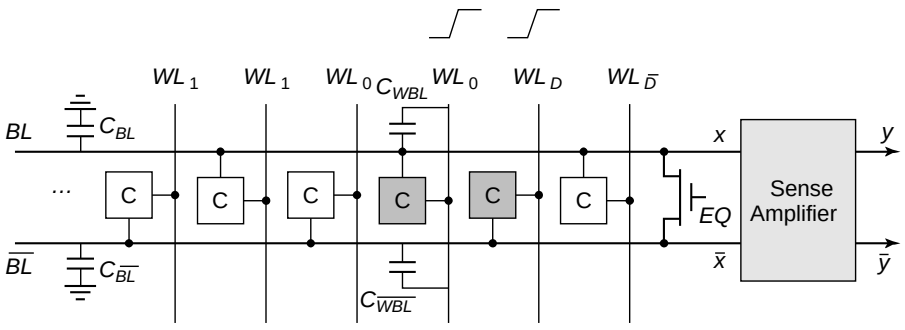
Noise Sources in 1T DRam



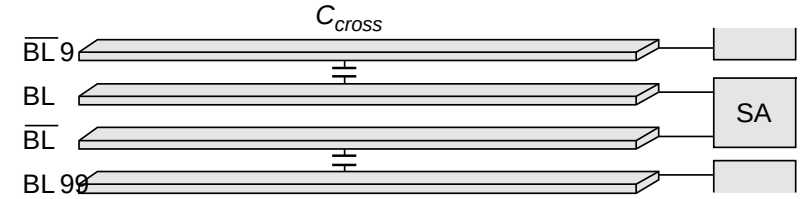
Open Bit-line Architecture —Cross Coupling



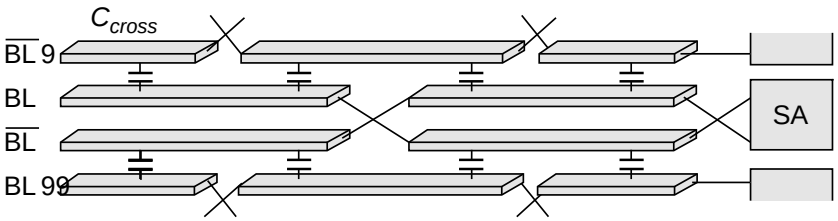
Folded-Bitline Architecture



Transposed-Bitline Architecture

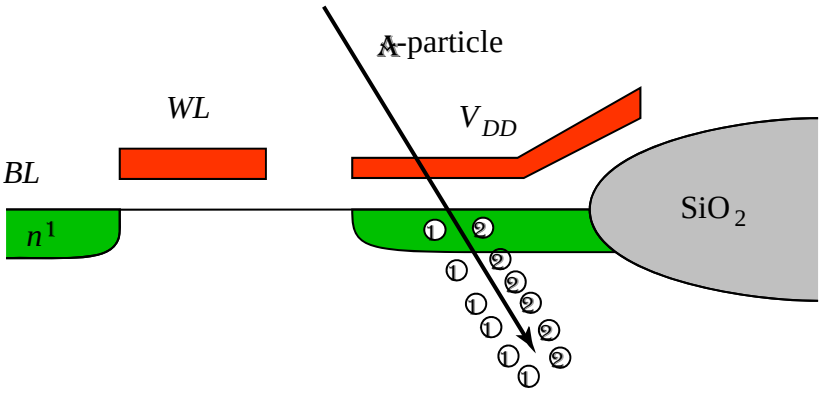


(a) Straightforward bit-line routing



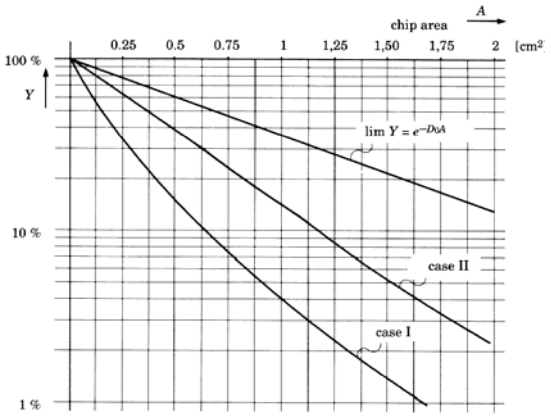
(b) Transposed bit-line architecture

Alpha-particles (or Neutrons)



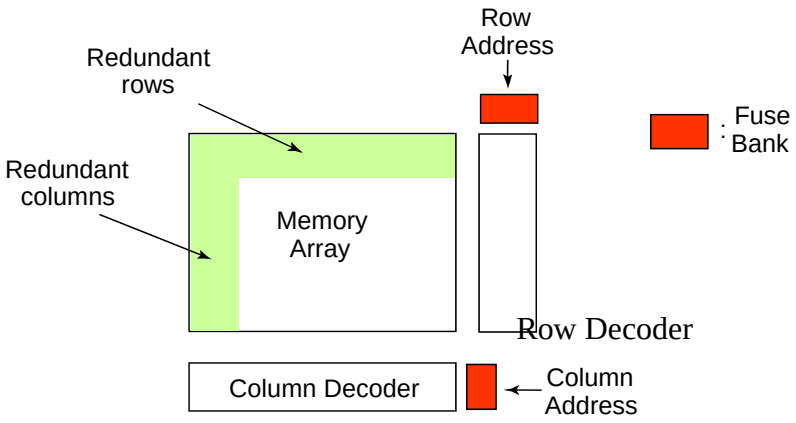
1 Particle ~ 1 Million Carriers

Yield



Yield curves at different stages of process maturity (from [Veendrick92])

Redundancy



Error-Correcting Codes

Example: Hamming Codes

$$P_1 P_2 B_3 P_4 B_5 B_6 B_7$$

with

$$P_1 \oplus B_3 \oplus B_5 \oplus B_7 = 0$$
$$P_2 \oplus B_3 \oplus B_6 \oplus B_7 = 0$$
$$P_4 \oplus B_5 \oplus B_6 \oplus B_7 = 0$$

e.g. B3 Wrong

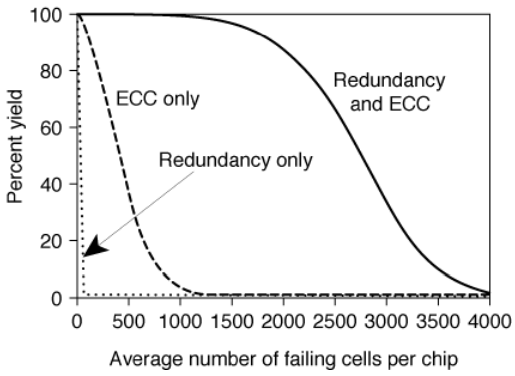
1

1

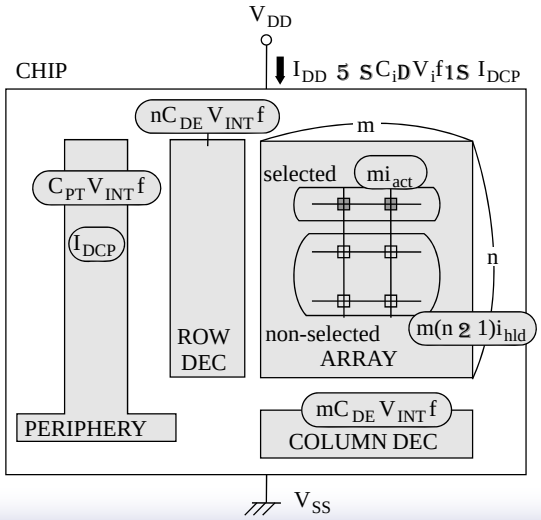
0

= 3

Redundancy and Error Correction

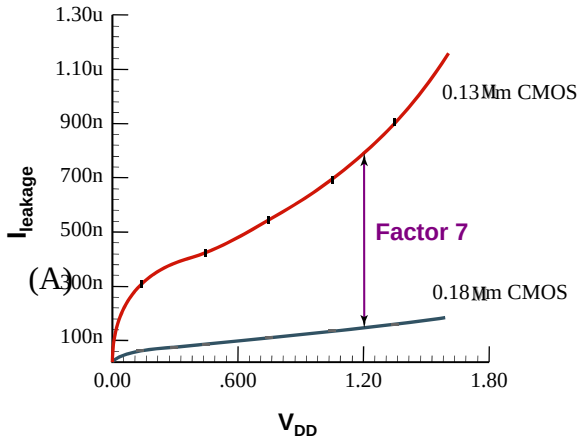


Sources of Power Dissipation in Memories



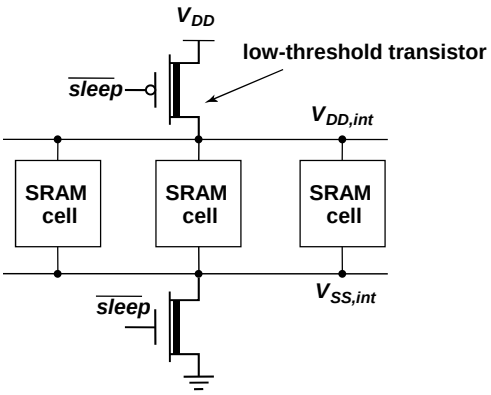
From [Itoh00]

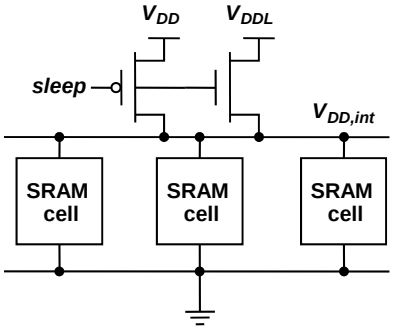
Data Retention in SRAM



SRAM leakage increases with technology scaling

Suppressing Leakage in SRAM

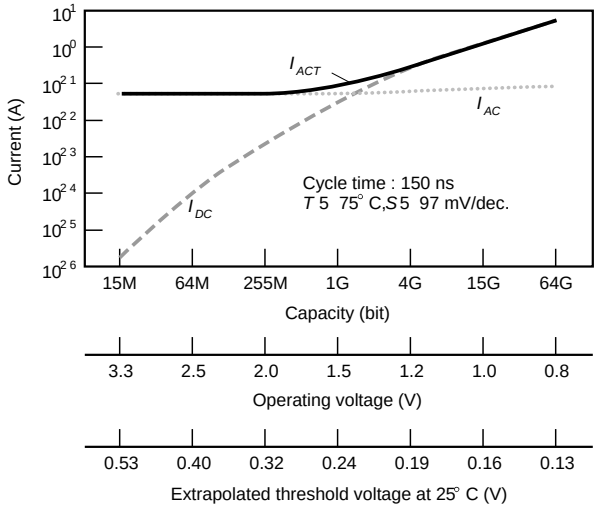




Inserting Extra Resistance

Reducing the supply voltage

Data Retention in DRAM



From [Itoh00]

Case Studies

- Programmable Logic Array
- SRAM
- Flash Memory

PLA versus ROM

- **Programmable Logic Array**
  structured approach to random logic
  "two level logic implementation"
  NOR-NOR (product of sums)
  NAND-NAND (sum of products)

IDENTICAL TO ROM!

- **Main difference**
  ROM: fully populated
  PLA: one element per minterm

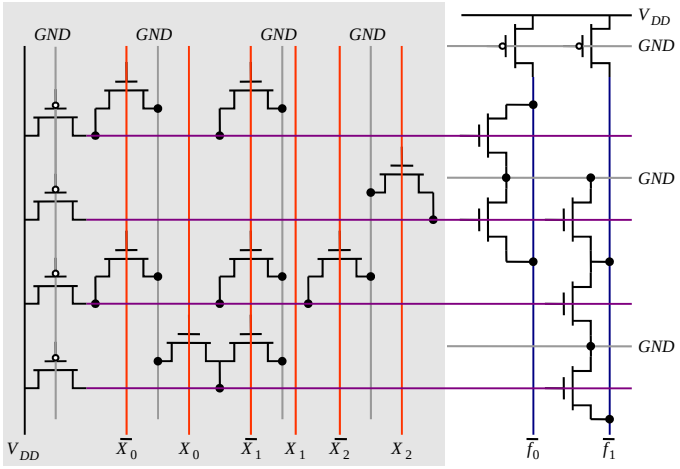
Note: Importance of PLA's has drastically reduced

1. **slow**
2. **better software techniques (mutli-level logic synthesis)**

But …

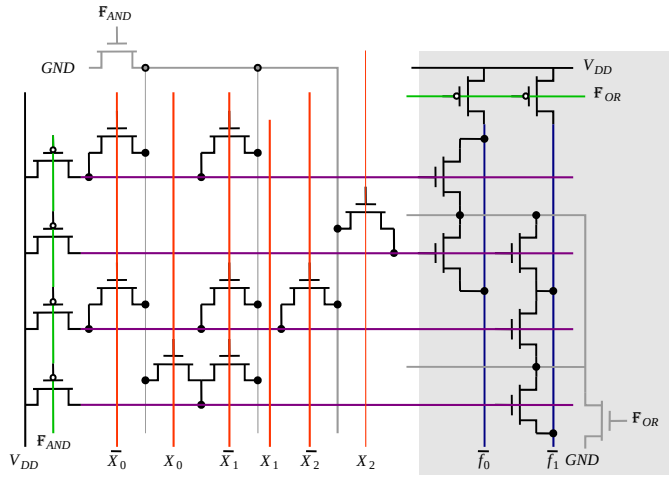
Programmable Logic Array

Pseudo-NMOS PLA



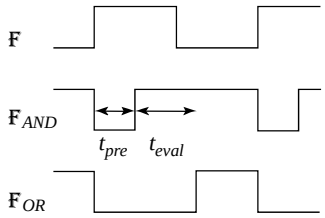
AND-plane **OR-plane**

Dynamic PLA

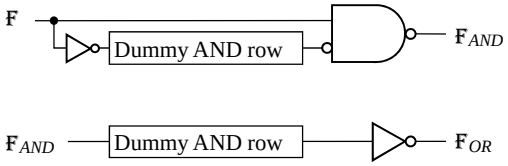


AND-plane **OR-plane**

Clock Signal Generation for self-timed dynamic PLA

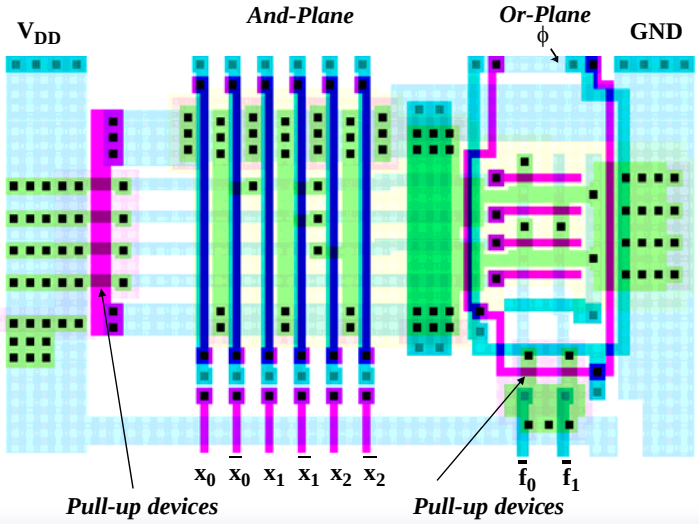


(a) Clock signals

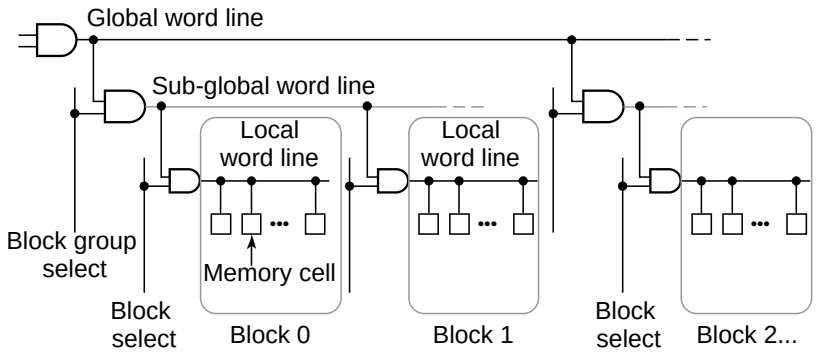


(b) Timing generation circuitry

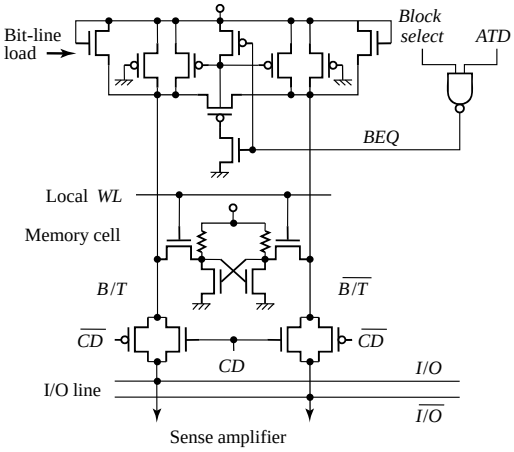
PLA Layout



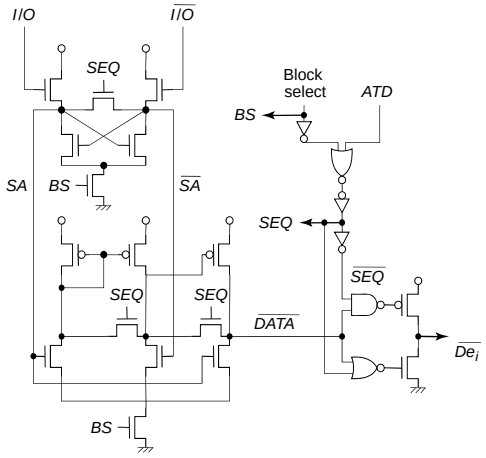
4 Mbit SRAM
Hierarchical Word-line Architecture

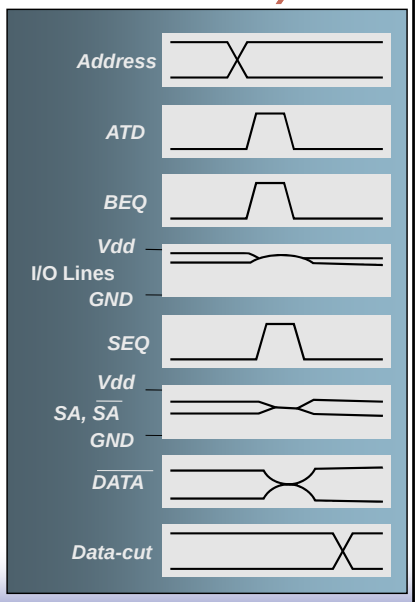


Bit-line Circuitry

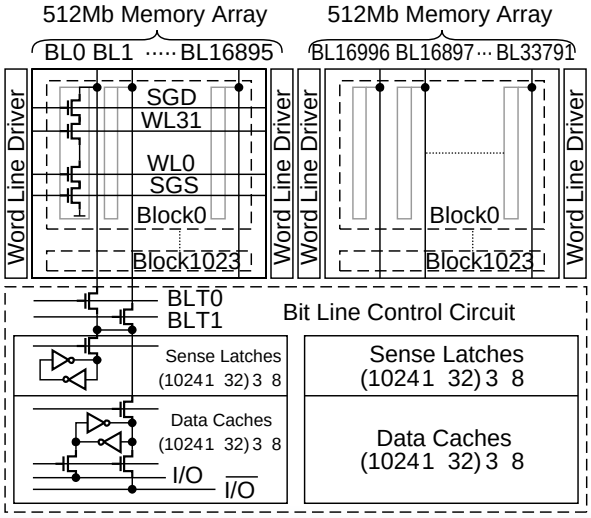


Sense Amplifier (and Waveforms)

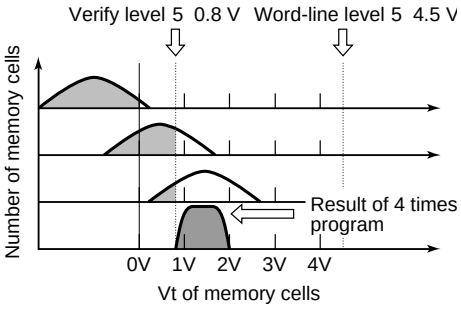




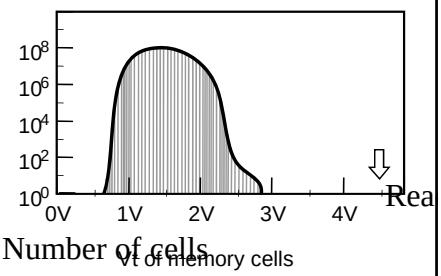
1 Gbit Flash Memory



Writing Flash Memory

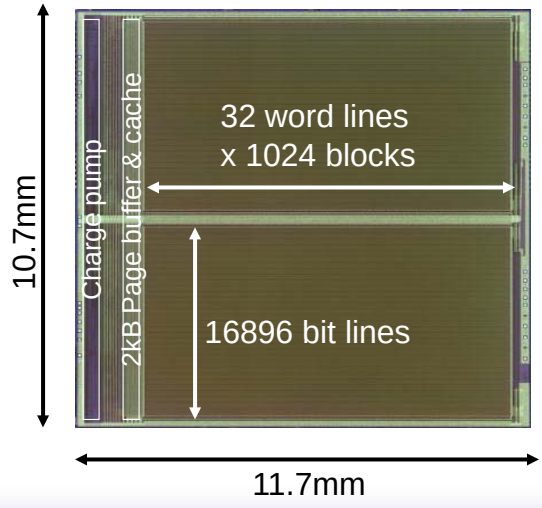


Evolution of thresholds



Final Distribution

125mm^2 1Gbit NAND Flash Memory

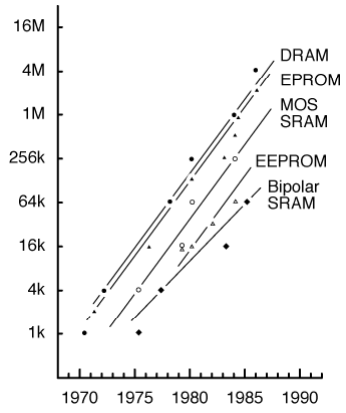


125mm^2 1Gbit NAND Flash Memory

- Technology 0.13μm p-sub CMOS triple-well 1poly, 1polycide, 1W, 2Al
- Cell size 0.077μm2
- Chip size 125.2mm2
- Organization 2112 x 8b x 64 page x 1k block
- Power supply 2.7V-3.6V
- Cycle time 50ns
- Read time 25μs
- Program time 200μs / page
- Erase time 2ms / block

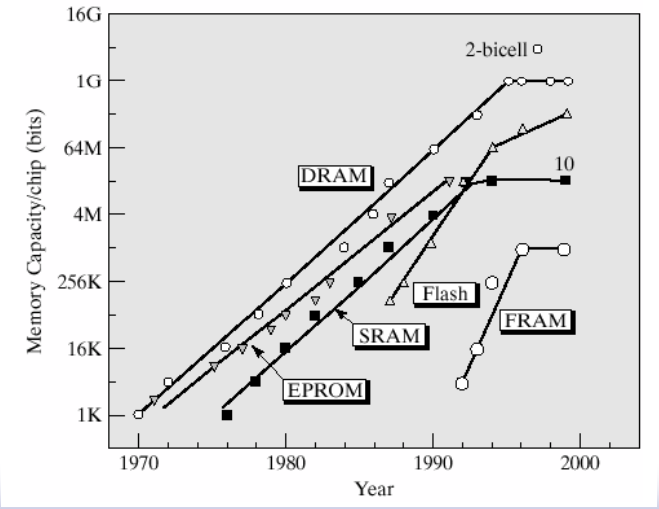
From [Nakamura02]

Semiconductor Memory Trends (up to the 90's)

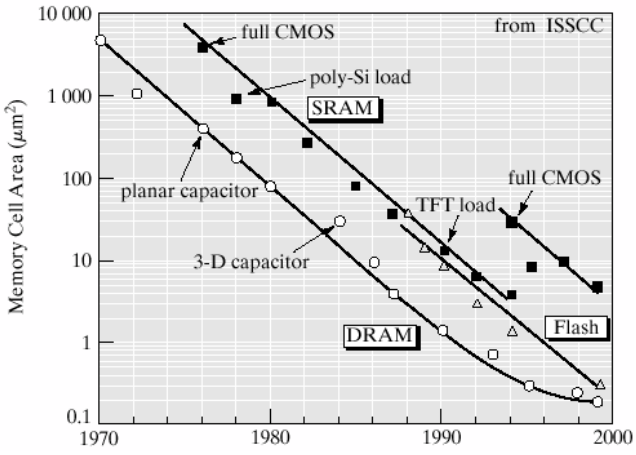


Memory Size as a function of time: x 4 every three years

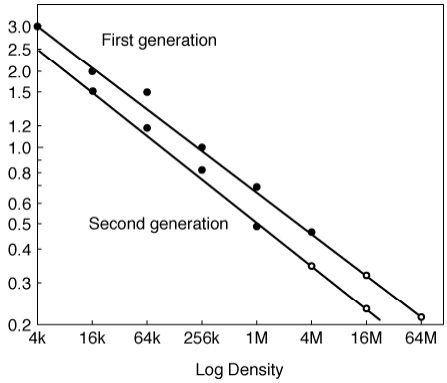
Semiconductor Memory Trends (updated)



Trends in Memory Cell Area



Semiconductor Memory Trends



Technology feature size for different SRAM generations